IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This docur level parts,	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information				
upplier Inforn	nation								,						
Company name*			Company unique ID			Unique ID Authority					Response Date*				
nsemi											2024-05-02				
Contact Name		7	Title - Contact			Phone - Contact*				Email - Contact*					
Product-Env-Stew	ards	I	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
authorized Represe	entative*	7	Title - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Request	Requester Item Number		Mfr Item Number Mfr Item Name			Effective D	ate V	ersion	Manufacturing Site		W	eight*	UOM	Unit Type	
		NCN26010XMNTXG 10BASE-T1S M. QFN-32			CPHY Ethernet controller	2024-05-02 PHG			43	3.244	mg	Each			
Ianufacturing	Process Information	n													
Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSL Rating		Peak Process Body Temperature Max Time at Peak				Temperatu	re Num	ber of Reflow Cyc	eles			
Matte Tin (Sn) - annealed			CU Alloy 1		260 C 30			seconds 3							
omments															
vel 1 - maximum	time at peak temperature o	during solde	ering is 10-30	0 seconds											
or more informati	ion regarding material con	nposition pl	ease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.904	mg	Supplier	Silicon (Si)	7440-21-3		2.904	mg
Die Attach	0.517	mg		Epoxy resin	proprietary data		0.0052	mg
			Supplier	Silver (Ag)	7440-22-4		0.3102	mg
			Supplier	Proprietary	Proprietary Data		0.0155	mg
			Supplier	Copper (Cu)	7440-50-8		0.1861	mg
Lead Frame	18.896	mg	Supplier	Silver (Ag)	7440-22-4		0.0113	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0246	mg
			Supplier	Iron (Fe)	7439-89-6		0.3968	mg
			Supplier	Copper (Cu)	7440-50-8		18.4482	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0151	mg
Mold Compound-Black	19.334	mg		Epoxy resin	proprietary data		0.9667	mg
			Supplier	Phenolic Resin	Proprietary Data		0.4447	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.9667	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0773	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.4447	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		16.4339	mg
Plating	1.458	mg	Supplier	Tin (Sn)	7440-31-5		1.458	mg
Wire Bond	0.135	mg	Supplier	Palladium (Pd)	7440-05-3		0.0028	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.1318	mg